

Title (en)

Thin film semiconductor device and fabrication method therefor

Title (de)

Dünnsfilm-Halbleiterbauelement und diesbezügliches Herstellungsverfahren

Title (fr)

Dispositif semiconducteur à couche mince et son procédé de fabrication

Publication

**EP 1517363 A2 20050323 (EN)**

Application

**EP 04255637 A 20040916**

Priority

JP 2003325781 A 20030918

Abstract (en)

A relaying pad is formed in a predetermined portion in an insulation layer of the single-crystal thin film device, in a region where the single-crystal thin film device is formed. The relaying pad is for providing connection wiring through the insulator substrate. With this configuration it is possible to prevent an increase in an aspect ratio of a contact hole formed in an insulation layer in a region in which a transferred device is formed, the semiconductor device including a substrate on which the transferred device and a deposited device coexist.

IPC 1-7

**H01L 21/336**; **H01L 29/786**

IPC 8 full level

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CPC (source: EP KR US)

**H01L 21/76254** (2013.01 - EP KR US); **H01L 21/76897** (2013.01 - EP KR US); **H01L 27/12** (2013.01 - KR); **H01L 27/1214** (2013.01 - KR); **H01L 27/124** (2013.01 - EP US); **H01L 27/1266** (2013.01 - EP KR US); **H01L 29/66757** (2013.01 - EP KR US); **H01L 29/66772** (2013.01 - EP KR US); **H01L 2221/68363** (2013.01 - EP KR US); **H01L 2224/24226** (2013.01 - EP KR US); **H01L 2924/01021** (2013.01 - EP KR US); **H01L 2924/1305** (2013.01 - EP US); **H01L 2924/13091** (2013.01 - EP US)

Cited by

FR3051971A1; US8008205B2; US8759842B2; US11114314B2

Designated contracting state (EPC)

DE FR GB

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**EP 1517363 A2 20050323**; **EP 1517363 A3 20060607**; JP 2005093757 A 20050407; JP 4651924 B2 20110316; KR 100737337 B1 20070710; KR 20050028871 A 20050323; US 2005067619 A1 20050331; US 7488980 B2 20090210

DOCDB simple family (application)

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